



Product Change Notification

Change Notification #: 116681 - 00
Change Title: Intel® RAID Module RMSP3CD080F,
PCN 116681-00, Product Design,
Resistor change and firmware update
Date of Publication: December 21, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*:	January 5, 2019
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® RAID Module RMSP3CD080F:

1. Change in resistor placement in the memory voltage regulator circuit order to allow 1.8V NOR flash memory. This is to allow a second source memory vendor.
2. Remove R46 and R51 resistors in order to fix the global activity LED issue.
3. Not to populate pull-up resistor in the Supercap charge circuit to increase charge circuit margin
4. Update the firmware to version 5.050.00-1367 (MR 7.5p2 on firmware package 50.5.2-1326)

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre TA#	Pre PBA#	Post TA#	Post PBA#
RMSP3CD080F	954489	J24903-004	J24905-202	J24903-005	J24905-203

PCN Revision History:

Date of Revision: December 21, 2018	Revision Number: 00	Reason: Originally Published PCN
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

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